

WHAT IS CLAIMED IS:

1. A fastening structure used to fastening a heat dissipating device with a printed circuit board in which a plurality of holes is formed, the fastening structure comprising a back plate disposed underneath the printed circuit board
5 and a plurality of fitting columns, wherein the back plate is perforated with a plurality of holes and the fitting columns each includes an elongate hollow tube and an insertion member projecting from a periphery of one end of the hollow tube, the hollow tube has a threaded internal sidewall and the insertion member has a shape conformal to the respective holes at which the fitting columns are
10 fixed to the back plate.

2. The structure of Claim 1, wherein the back plate is fabricated from metal or plastic material.

3. The structure of Claim 1, wherein the holes are hexagonal or rectangular.

15 4. The structure of Claim 1, wherein the back plate includes a plurality of slots formed along a periphery thereof.

5. The structure of Claim 4, wherein the slots includes a pair of T-shape slots formed at two opposing sides of the periphery.

20 6. The structure of Claim 1, wherein the fitting columns are formed of metal material.

7. The structure of Claim 1, wherein the insertion member of each fitting column includes a groove recessed from a periphery thereof.

8. The structure of Claim 7, further comprising a washer to be inserted into the groove, the washer has a diameter larger than that of the insertion
25 member.

9. The structure of Claim 1, further comprising a bottom lid attached to a bottom of each insertion member, the bottom lid has a diameter larger than that of the insertion member.

10. The structure of Claim 1, further comprises screw members to fasten the fitting columns with the back plate.

11. The structure of Claim 1, wherein the heat dissipating device is mounted on the printed circuit board such that the printed circuit board is
5 sandwiched by the heat dissipating device and the back plate.

12. The structure of Claim 11, wherein the heat dissipating device includes a frame with a perforation placed on the printed circuit board, a thermal conductive block placed aligned over the perforation, a bracket having a central member place on the thermal conductive block and two bracket members
10 extending from the central member to be placed between a periphery of the frame and the printed circuit board, and a heat sink disposed across the thermal conductive block.

13. The structure of Claim 12, wherein the periphery of frame is perforated with holes allowing the fitting columns to extend therethrough.

14. The structure of Claim 12, further comprises a plurality of screw
15 members to fasten the fitting columns with the frame.

15. The structure of Claim 14, further comprises a plurality of resilient members between the frame and heads of the screw members.